

## N-Channel Super Junction Power MOSFET III

### General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

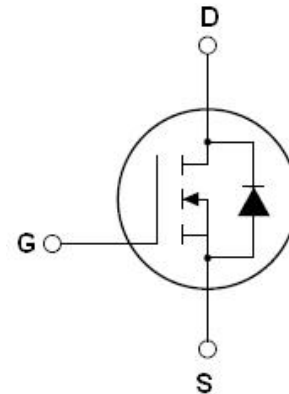
### Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

### Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

$V_{DS}$	700	V
$R_{DS(ON)TYP.}$	1100	m $\Omega$
$I_D$	4	A



Schematic diagram

### Package Marking And Ordering Information

Device	Device Package	Marking
NCE70T1K2R	SOT-223-2L	NCE70T1K2R



SOT-223-2L

Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	700	V
Gate-Source Voltage ( $V_{DS}=0V$ ), AC ( $f>1$ Hz)	$V_{GS}$	$\pm 30$	V
Gate-Source Voltage ( $V_{DS}=0V$ )	$V_{GS}$	$\pm 20$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_{D(DC)}$	4	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_{D(DC)}$	2.5	A
Pulsed drain current (Note 1)	$I_{DM(pluse)}$	16	A
Maximum Power Dissipation( $T_c=25^\circ\text{C}$ )	$P_D$	5.2	W
Single pulse avalanche energy (Note2)	$E_{AS}$	27	mJ
Avalanche current(Note 1)	$I_{AS}$	0.7	A
Repetitive Avalanche energy, $t_{AR}$ limited by $T_{jmax}$	$E_{AR}$	0.1	mJ

(Note 1)			
Parameter	Symbol	Value	Unit
Drain Source voltage slope, $V_{DS} \leq 480V$ ,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leq 480V, I_{SD} < I_D$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+150	°C

**Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	24	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	62	°C/W

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

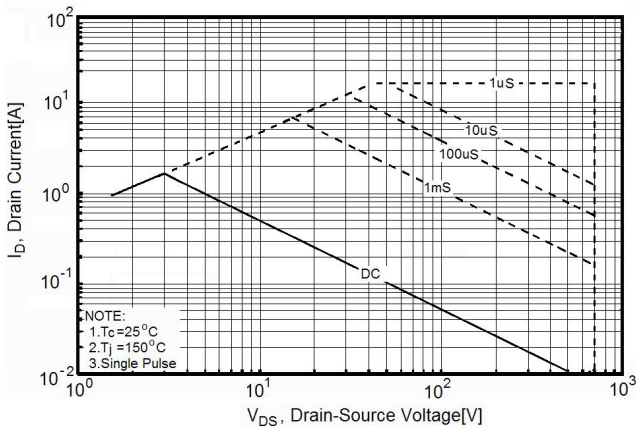
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On/off states</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	700			V
Zero Gate Voltage Drain Current( $T_C=25^\circ C$ )	$I_{DSS}$	$V_{DS}=700V, V_{GS}=0V$			1	$\mu A$
Zero Gate Voltage Drain Current( $T_C=125^\circ C$ )	$I_{DSS}$	$V_{DS}=700V, V_{GS}=0V$			50	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	3		4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=2A$		1100	1300	m $\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V,$ $F=1.0MHz$		304	350	PF
Output Capacitance	$C_{oss}$			17		PF
Reverse Transfer Capacitance	$C_{rss}$			0.5		PF
Total Gate Charge	$Q_g$	$V_{DS}=480V, I_D=4A,$ $V_{GS}=10V$		8.8	12	nC
Gate-Source Charge	$Q_{gs}$			2.3		nC
Gate-Drain Charge	$Q_{gd}$			4		nC
<b>Switching times</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=380V, I_D=2.5A,$ $R_G=5\Omega, V_{GS}=10V$		8		nS
Turn-on Rise Time	$t_r$			4		nS
Turn-Off Delay Time	$t_{d(off)}$			52	70	nS
Turn-Off Fall Time	$t_f$			9	18	nS
<b>Source- Drain Diode Characteristics</b>						
Source-drain current(Body Diode)	$I_{SD}$	$T_C=25^\circ C$			4	A
Pulsed Source-drain current(Body Diode)	$I_{SDM}$				16	A
Forward On Voltage	$V_{SD}$	$T_J=25^\circ C, I_{SD}=4A, V_{GS}=0V$		0.9	1.2	V
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C, I_F=2A, di/dt=100A/\mu s$		200		nS
Reverse Recovery Charge	$Q_{rr}$			0.6		$\mu C$
Peak reverse recovery current	$I_{rrm}$			6		A

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

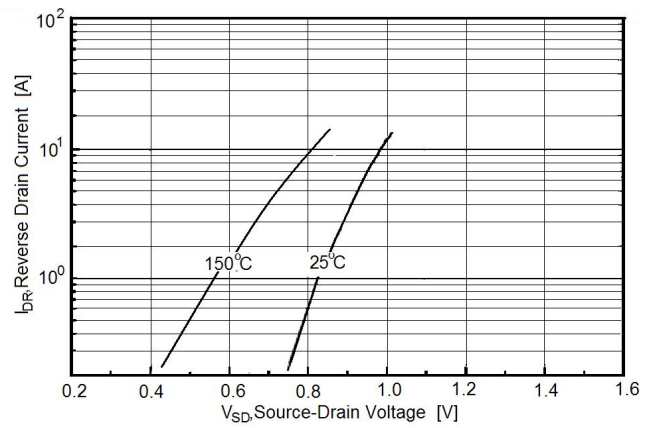
2.  $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega$

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

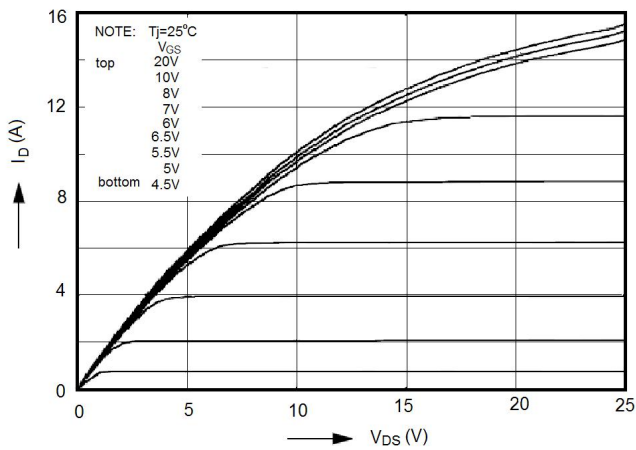
**Figure1. Safe operating area**



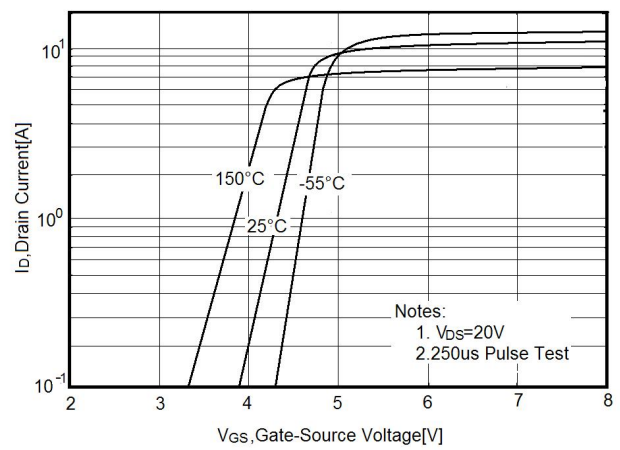
**Figure2. Source-Drain Diode Forward Voltage**



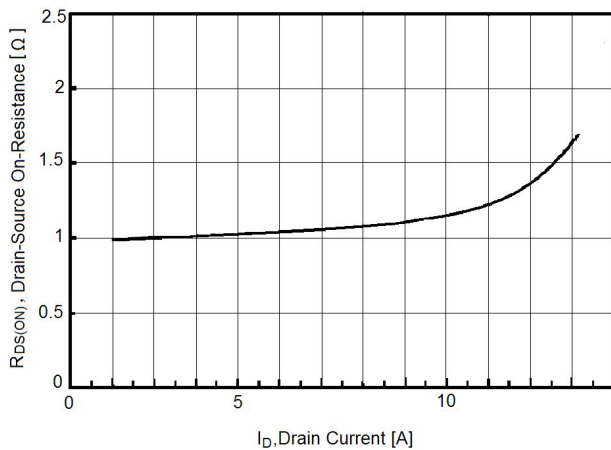
**Figure3. Output characteristics**



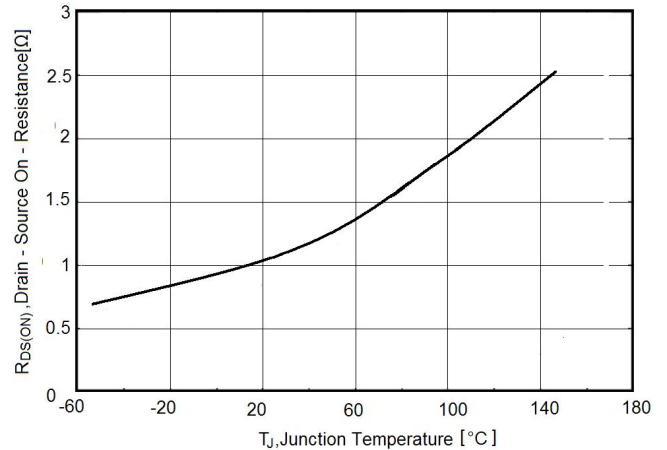
**Figure4. Transfer characteristics**



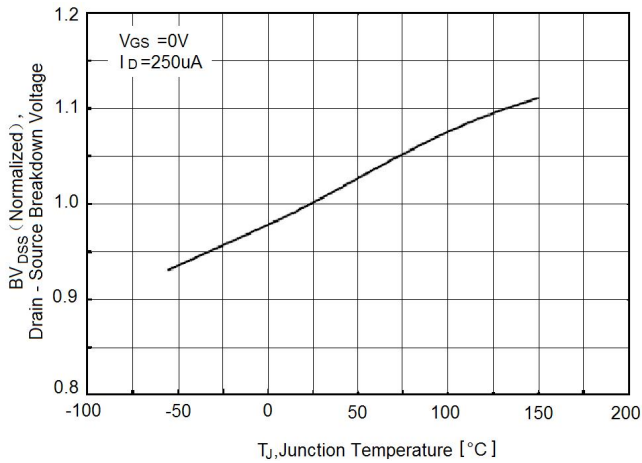
**Figure5. Static drain-source on resistance**



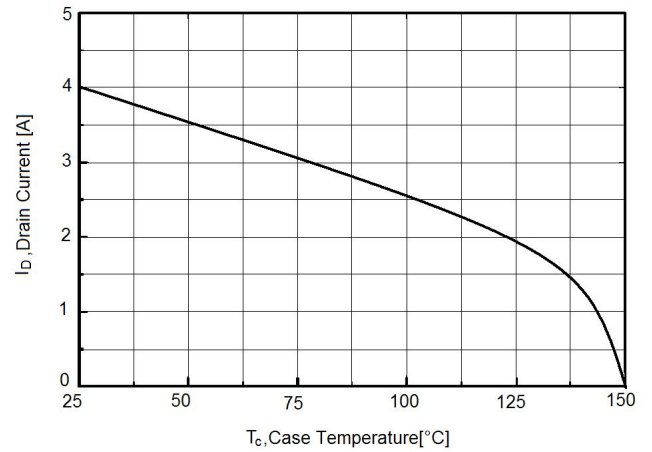
**Figure6.  $R_{DS(ON)}$  vs Junction Temperature**



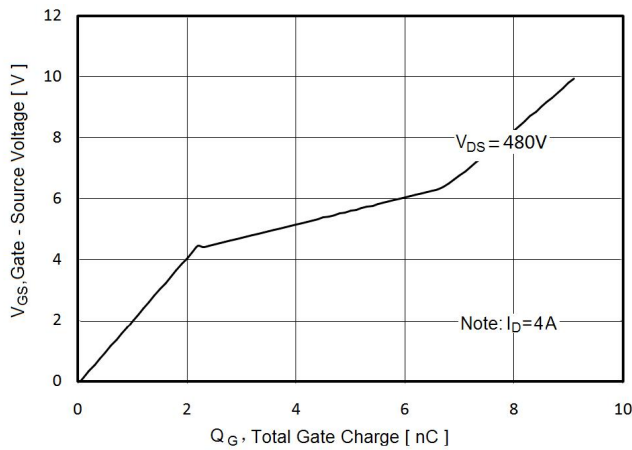
**Figure7.  $BV_{DSS}$  vs Junction Temperature**



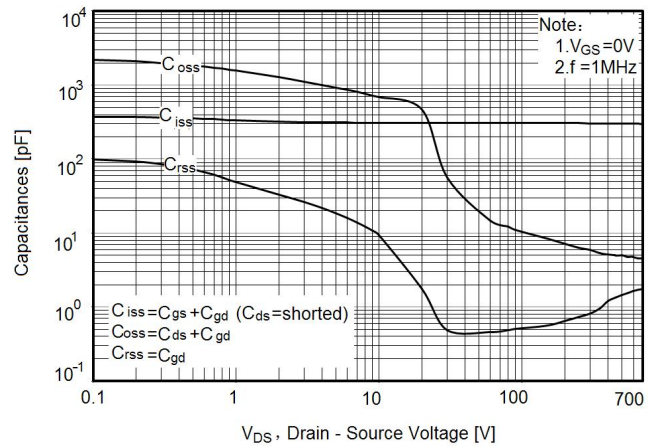
**Figure8. Maximum  $I_D$  vs Junction Temperature**



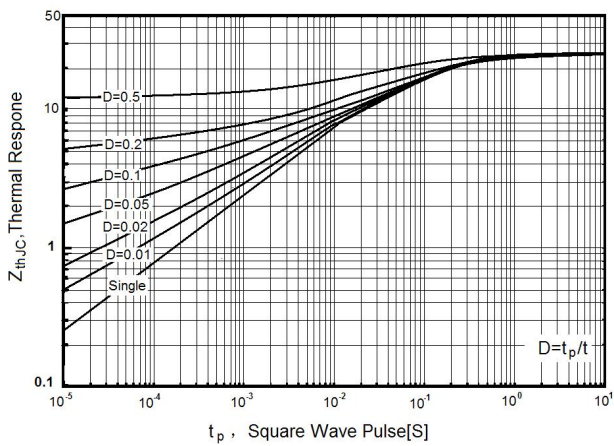
**Figure9. Gate charge waveforms**



**Figure10. Capacitance**



**Figure11. Transient Thermal Impedance**

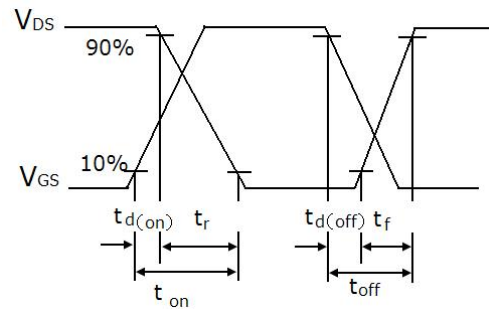


## Test circuit

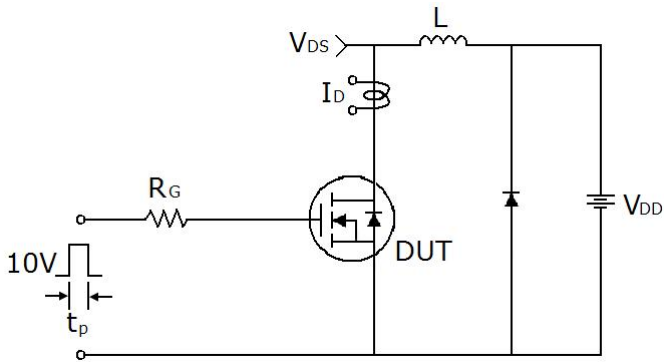
### 1) Gate charge test circuit & Waveform



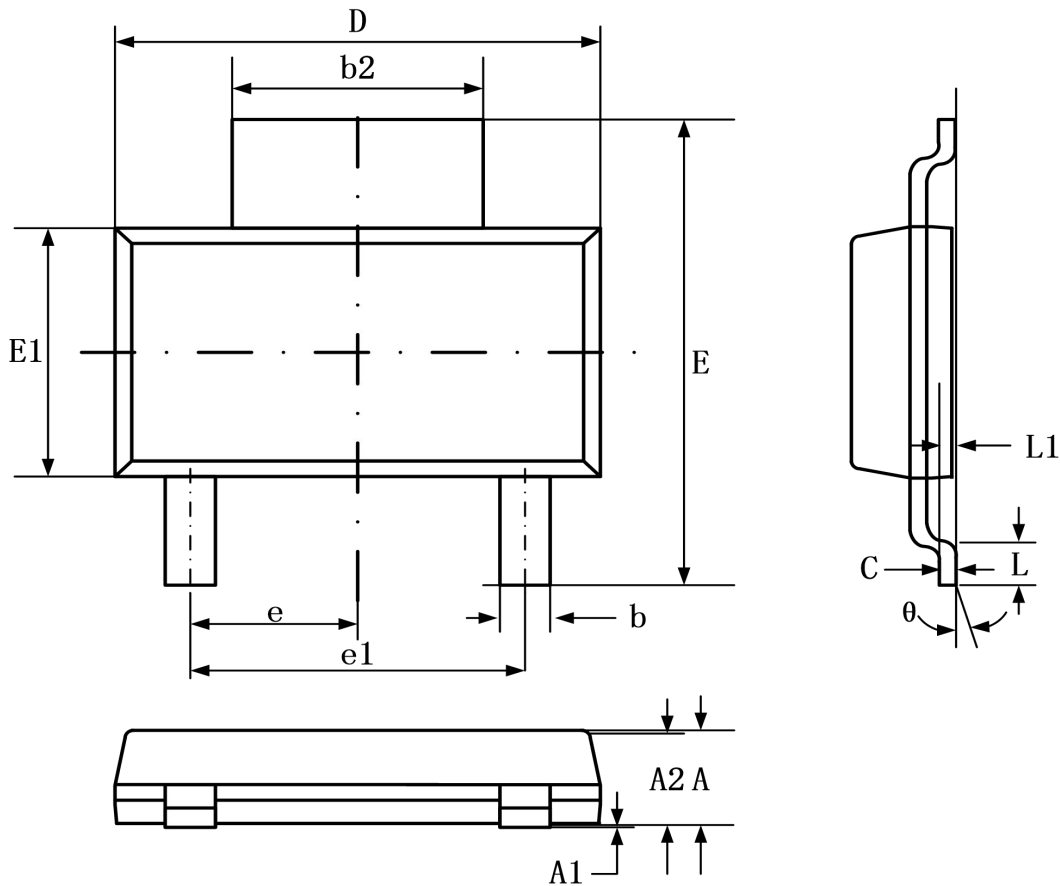
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms

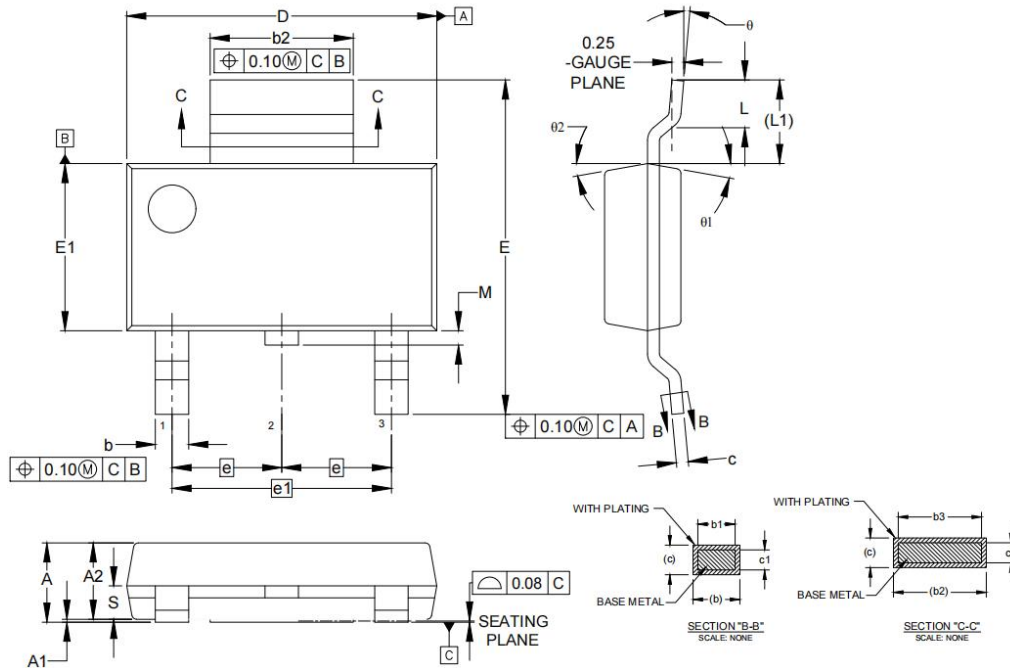


### SOT-223-2L-B Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	---	1.80	---	0.071
A1	0.02	0.10	0.001	0.004
A2	1.50	1.70	0.059	0.067
b	0.66	0.84	0.026	0.033
b2	2.90	3.10	0.114	0.122
c	0.23	0.35	0.009	0.014
D	6.30	6.70	0.248	0.264
E	6.70	7.30	0.264	0.287
E1	3.30	3.70	0.130	0.146
e	2.30 BSC.		0.091 BSC.	
e1	4.60 BSC.		0.182 BSC.	
L	0.81	---	0.032	---
L1	0.25 BSC.		0.032 BSC.	
$\theta$	0°	10°	0°	10°

# SOT-223-2L-J Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.52	1.80	0.060	0.071
A1	0.02	0.10	0.001	0.004
A2	1.50	1.70	0.059	0.067
b	0.60	0.80	0.024	0.031
b1	0.60	0.78	0.024	0.031
b2	2.95	3.10	0.116	0.122
b3	2.95	3.05	0.116	0.120
c	0.24	0.32	0.009	0.013
c1	0.24	0.30	0.009	0.012
D	6.30	6.70	0.248	0.264
E	6.70	7.30	0.264	0.287
E1	3.30	3.70	0.130	0.146
e	2.30 BSC.		0.091 BSC.	
e1	4.60 BSC.		0.182 BSC.	
L	0.90	1.10	0.035	0.043
L1	1.75 REF		0.069 REF	
M	---	0.50	---	0.020
S	0.70 REF		0.028 REF	
θ	0°	10°	0°	10°
θ1	10° REF		10° REF	
θ2	10° REF		10° REF	

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